

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	ENCAPSULATED PIN STRUCTURE FOR IMPROVED RELIABILITY OF WAFER
--------------------	--

Application Number :

Confirmation Number:

First Named Applicant: Tien-Jen Cheng

Attorney Docket Number: FIS920030103US1

Art Unit:

Examiner:

Search string: (5773889 or 5989935 or 6300236 or 6449840 or 6500324 or 20020179689).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5773889	1998-06-30	LOVE, ET AL.			
	2	5989935	1999-11-23	ABBOTT			
	3	6300236	2001-10-09	HARPER, ET AL.			
	4	6449840	2002-09-17	LE, ET AL.			
	5	6500324	2002-12-31	SIMPSON, ET AL.			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020179689	2002-12-05	TUNG			

Signature

Examiner Name	Date